IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005, IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						als and Mfg	Informat	ion	
Supplier Infor	mation														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
nsemi												2023-06-08			
Contact Name		Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-Env-Stev	wards	Product Enviro Compliance]	NA					Product-Env-Stewards@onsemi.com				
Authorized Repre	sentative*	Title - Representative			F	Phone - Representative*				Email - Representative*					
Product-Env-Stev	wards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com					
Reques	ster Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	ersion Manufacturing Site		W	eight*	UOM	Unit Type	
		NCV7240BDPR2G		Automotive Driver			2023-06-08	08 PH1			154.621 mg		Each		
Ianufacturing	g Proccess Informati	on													
Termina	al Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 MS	MSL Rating Peal		eak Process Body Temperature		e Max Tim	e at Peak	Temperatu	e Numb	er of Reflow Cyc	eles
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 2		2		260		C 30			second	seconds 3		
Comments															
TTENTION: MS	SL 2 Rated item requires	Dry Pack (after electrical	l test)											
or more informa	tion regarding material co	omposition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier is liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.23	mg	Supplier	Silicon (Si)	7440-21-3		4.23	mg
Die Attach	0.879	mg	Supplier	Silver (Ag)	7440-22-4		0.6593	mg
			Supplier	Epoxy resins	129915-35-1		0.2198	mg
Lead Frame	64.67		Supplier	Zinc (Zn)	7440-66-6		0.0647	mg
			Supplier	Iron (Fe)	7439-89-6		1.4874	mg
			Supplier	Copper (Cu)	7440-50-8		63.0532	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0647	mg
Mold Compound-Black	83.88			Epoxy resin	proprietary data		6.291	mg
			Supplier	Phenolic Resin	Proprietary Data		2.097	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		6.291	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4194	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		68.7816	mg
Plating	0.602	mg	Supplier	Palladium (Pd)	7440-05-3		0.0464	mg
			В	Nickel (Ni)	7440-02-0		0.5496	mg
			Supplier	Gold (Au)	7440-57-5		0.006	mg
Wire Bond - Au	0.36	mg	Supplier	Gold (Au)	7440-57-5		0.36	mg